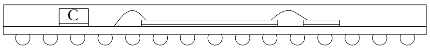
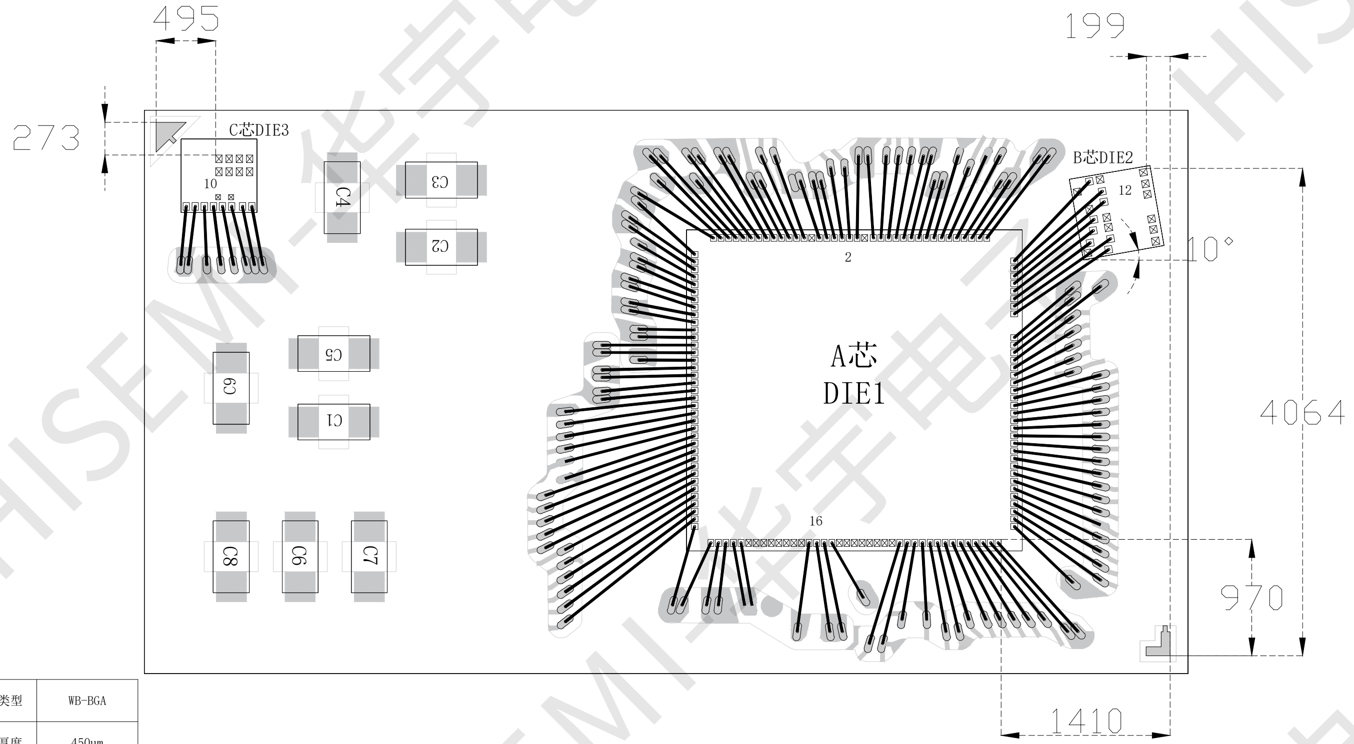
池州华宇电子科技股份有限公司
CHI ZHOU HISEMI ELECTRONICS TECHNOLOGY CO.,LTD

焊线图纸 Bonding Diagram

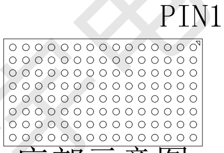
客户代码 Customer No.	1315	线图号 Drawing No.	HY-PX-1315-001 A			页码 Page	2 / 5
产品名称 Product Type	CS1516		封装外型 PKG Type	WBBGA120B(8.7X4.7X0.85-P0.565)			
焊线种类 Wire Type	焊线直径(μm) Wire Diameter	焊线根数 NO. of wire	焊线总长(μm) Total wire length	最长线长(μm) Longest wire length	最短线长(μm) Shortest wire length	塑封料型号(绿色环保) Compound Type (Green)	基板编码 Substrate No.
金钯铜丝 PdAuCu	18	137	133915	1390	269	首选(Preferred)：G311ACCver.GR 备选(Optional)：	WBBGA120B(087047)1315001
客户图号 Customer drawing NO.							

样品验证，禁止量产！



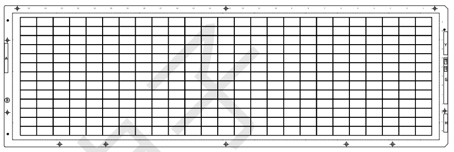


封装类型	WB-BGA
塑封厚度	450um
锡球型号/尺寸	SAC305 /300um
基板切割道	200um
基板厚度	170um



底部示意图

框架传送方向（装片）：
L/F Direction（D/A）：上侧三个圆孔



实物图：
Chip photo：

特殊说明 Special Instructions：

DB注意：
1.装片位置公差为±25um；
2.B芯DIE2 逆时针旋转10°；
3.控制溢胶，为WB预留焊线位置；避免溢胶到finger。

WB注意：
1.数字代表不打线pad数量。

说明 Instructions	粘片胶类型 epoxy type	芯片名称 Die name	芯片尺寸 (Without Saw street)	最小焊盘尺寸 Min BPO (μm²)	最小焊盘间距 Min BPP(μm)	铝垫厚度(μm) Pad Thickness	焊盘下是否有电路 Circuit under Pad	划片道宽度 Street line (μm)	晶圆尺寸 Wafer Size	是否激光切割 If laser ?	减薄厚度 (μm) Wafer Thickness
A芯：DIE 1	绝缘胶 (Non-conductive) 2025DSI	XYNILB0	2799*2677.5(μm²) 110.196*105.5(mil²)	56.7*49.5	62	2.8	YES/是	62	12	YES/low-k 55nm	100
B芯：DIE 2	绝缘胶 (Non-conductive) 2025DSI	P25Q21HBWF	742*742μm²) 29.22*29.22(mil²)	60.3*60.3	80	2.8	YES/是	60	12	NO/否 55nm	100
C芯：DIE 3	绝缘胶 (Non-conductive) 2025DSI	P24C128HWF	633*612μm²) 24.93*24.09(mil²)	54*64.8	65	2.8	YES/是	60	12	YES/low-k 55nm	100

拟制 Prepared by	NING LIN	制图日期 Create Date	2025/11/21	生效日期 Effective Date		客户确认签字/盖章：Customer Signature
研发审核 R&d check		产品工程审核 Product engineering check		批准 Approved by		

*温馨提示：图纸为产品下线生产的唯一依据，请您认真确认，我司依据您回签后的图纸生产，如图纸错误会产生不可估量损失，谢谢！
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